

ABSTRACT

A first semiconductor chip (1) of a high withstand voltage and a second semiconductor chip (2) of a low withstand voltage are connected to each other in a package (3). The first semiconductor chip (1) has a voltage conversion circuit (4), a plurality of first inter-chip connection portions (10) for connection to the second semiconductor chip (2), a first serial decoder (6), and external connection portions (13) for connection to the external connection terminals (12) led out of the package (3). The second semiconductor chip (2) has a second serial decoder (5) and a plurality of second inter-chip connection portions (11) for connection to the first semiconductor chip (1). Bonding wires (9) are provided which directly connect the plurality of first inter-chip connection portions (10) and the plurality of second inter-chip connection portions (11) to each other.